OMB No. 0651-0027 (exp. 6/30/2008)	29 - 2005 U.S. DEPARTMENT OF COMMERCE	
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1. Name of conveying party(ies)	2. Name and address of receiving party(ies)	
1) SHIMIZU, Noriyoshi	Name: SHINKO ELECTRIC INDUSTRIES	
2) YAMASAKI, Tomoo	00 4.572	
3) OI, Kiyoshi	<u> </u>	
4) ROKUGAWA, Akio Additional name(s) of conveying party(ies) attached? Yes N	o RO Ochimadamachi	
3. Nature of conveyance/Execution Date(s):	Street Address: 80, Oshimadamachi,	
Execution Date(s) December 7, 2005 Assignment Merger	Nagano-shi, Nagano 381-2287 Japan	
	City:	
Security Agreement Change of Name		
Joint Research Agreement Government Interest Assignment	State:	
Executive Order 9424, Confirmatory License	Country: Zip:	
Other	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	
	Additional name(s) & address(es) attached? Yes Yes document is being filed together with a new application.	
A. Patent Application No.(s)	B. Patent No.(s)	
01 FC:8 21 40.00 DP Additional numbers a	attached? Yes No	
5. Name and address to whom correspondence concerning document should be mailed: Name: Richard J. Streit	6. Total number of applications and patents involved:1	
Name: Richard J. Strett	7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00	
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Street Address: c/o Ladas & Parry LLP	Enclosed	
224 South Michigan Avenue	None required (government interest not affecting title)	
224 South Michigan Avenue City: Chicago	None required (government interest not affecting title) 8. Payment Information	
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Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:
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PATENT REEL: 017396 FRAME: 0412

UNITED STATES OF AMERICA ASSIGNMENT

In consideration of the payment of ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for the other good and valuable consideration,

ASSIGNOR:

- (1) Noriyoshi SHIMIZU, (2) Tomoo YAMASAKI, (3) Kiyoshi OI and
- (4) Akio ROKUGAWA,

residing at each c/o SHINKO ELECTRIC INDUSTRIES CO., LTD.,

80, Oshimadamachi, Nagano-shi, Nagano 381-2287 Japan

hereby sells, assigns and transfers to

ASSIGNEE:

SHINKO ELECTRIC INDUSTRIES CO., LTD. having a place of business at: 80, Oshimadamachi, Nagano-shi, Nagano 381-2287 Japan

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the Application entitled

METHOD OF MANUFACTURING WIRING SUBSTRATE TO WHICH SEMICONDUCTOR CHIP IS MOUNTED

which application was

RECORDED: 12/19/2005

(a)	executed by the un-	dersigned on	December 7,	2005
(b)	filed as Serial No.		on	

and, in and to all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and

Page 1 of 2

PATENT REEL: 017396 FRAME: 0413